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What is "Embedded - Microcontrollers"?

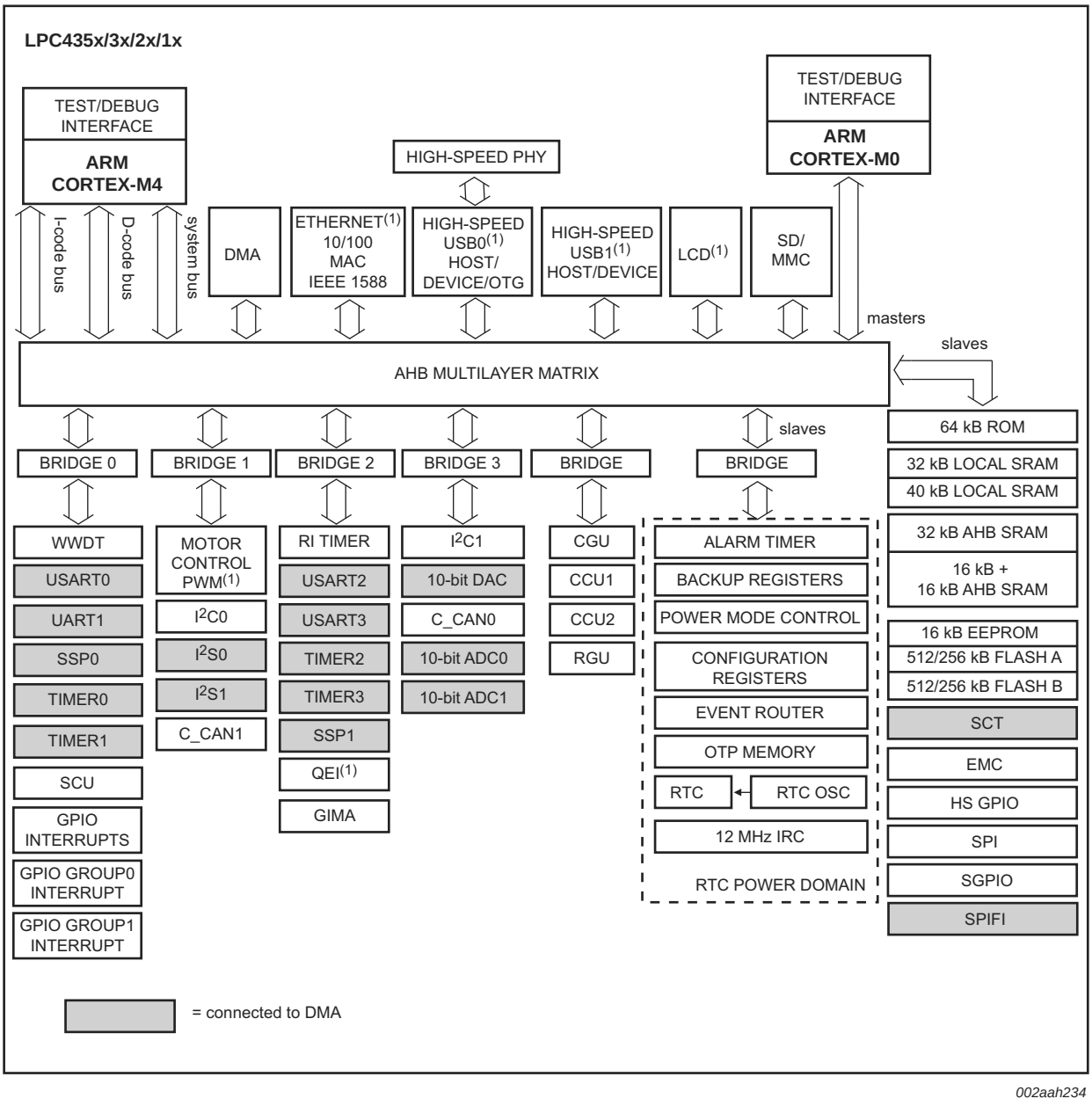
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4/M0
Core Size	32-Bit Dual-Core
Speed	204MHz
Connectivity	CANbus, EBI/EMI, I²C, IrDA, Microwire, SD, SPI, SSI, SSP, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, WDT
Number of I/O	49
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	16K x 8
RAM Size	104K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 3.6V
Data Converters	A/D 4x10b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TFBGA
Supplier Device Package	100-TFBGA (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc4312jet100e

- Cortex-M0 Processor core
  - ARM Cortex-M0 co-processor (version r0p0) capable of off-loading the main ARM Cortex-M4 application processor.
  - Running at frequencies of up to 204 MHz.
  - JTAG
  - Built-in NVIC.
- On-chip memory
  - Up to 1 MB on-chip dual bank flash memory with flash accelerator.
  - 16 kB on-chip EEPROM data memory.
  - 136 kB SRAM for code and data use.
  - Multiple SRAM blocks with separate bus access. Two SRAM blocks can be powered down individually.
  - 64 kB ROM containing boot code and on-chip software drivers.
  - 64 bit+ 256 bit of One-Time Programmable (OTP) memory for general-purpose use.
- Configurable digital peripherals
  - Serial GPIO (SGPIO) interface.
  - State Configurable Timer (SCTimer/PWM) subsystem on AHB.
  - Global Input Multiplexer Array (GIMA) allows to cross-connect multiple inputs and outputs to event driven peripherals like the timers, SCTimer/PWM, and ADC0/1.
- Serial interfaces
  - Quad SPI Flash Interface (SPIFI) with four lanes and up to 52 MB per second.
  - 10/100T Ethernet MAC with RMII and MII interfaces and DMA support for high throughput at low CPU load. Support for IEEE 1588 time stamping/advanced time stamping (IEEE 1588-2008 v2).
  - One High-speed USB 2.0 Host/Device/OTG interface with DMA support and on-chip high-speed PHY.
  - One High-speed USB 2.0 Host/Device interface with DMA support, on-chip full-speed PHY and ULPI interface to external high-speed PHY.
  - USB interface electrical test software included in ROM USB stack.
  - One 550 UART with DMA support and full modem interface.
  - Three 550 USARTs with DMA and synchronous mode support and a smart card interface conforming to ISO7816 specification. One USART with IrDA interface.
  - Up to two C_CAN 2.0B controllers with one channel each.
  - Two SSP controllers with FIFO and multi-protocol support. Both SSPs with DMA support.
  - One SPI controller.
  - One Fast-mode Plus I^2C-bus interface with monitor mode and with open-drain I/O pins conforming to the full I^2C-bus specification. Supports data rates of up to 1 Mbit/s.
  - One standard I^2C-bus interface with monitor mode and with standard I/O pins.
  - Two I^2S interfaces, each with DMA support and with one input and one output.
- Digital peripherals
  - External Memory Controller (EMC) supporting external SRAM, ROM, NOR flash, and SDRAM devices.

5. Block diagram



(1) Not available on all parts. See Table 2.

Fig 1. LPC435x/3x/2x/1x Block diagram

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
P1_16	M7	H9	90	64	[2]	N; PU	I/O	**GPIO0[3] —** General purpose digital input/output pin.
							I	**U2_RXD —** Receiver input for USART2.
							I/O	**SGPIO3 —** General purpose digital input/output pin.
							I	**ENET_CRS —** Ethernet Carrier Sense (MII interface).
							O	**T0_MAT0 —** Match output 0 of timer 0.
							-	**R —** Function reserved.
							I/O	**EMC_D9 —** External memory data line 9.
							I	**ENET_RX_DV —** Ethernet Receive Data Valid (RMII/MII interface).
P1_17	M8	H10	93	66	[3]	N; PU	I/O	**GPIO0[12] —** General purpose digital input/output pin.
							I/O	**U2_UCLK —** Serial clock input/output for USART2 in synchronous mode.
							-	**R —** Function reserved.
							I/O	**ENET_MDIO —** Ethernet MIIM data input and output.
							I	**T0_CAP3 —** Capture input 3 of timer 0.
							O	**CAN1_TD —** CAN1 transmitter output.
							I/O	**SGPIO11 —** General purpose digital input/output pin.
							-	**R —** Function reserved.
P1_18	N12	J10	95	67	[2]	N; PU	I/O	**GPIO0[13] —** General purpose digital input/output pin.
							I/O	**U2_DIR —** RS-485/EIA-485 output enable/direction control for USART2.
							-	**R —** Function reserved.
							O	**ENET_TXD0 —** Ethernet transmit data 0 (RMII/MII interface).
							O	**T0_MAT3 —** Match output 3 of timer 0.
							I	**CAN1_RD —** CAN1 receiver input.
							I/O	**SGPIO12 —** General purpose digital input/output pin.
							I/O	**EMC_D10 —** External memory data line 10.
P1_19	M11	K9	96	68	[2]	N; PU	I	**ENET_TX_CLK (ENET_REF_CLK) —** Ethernet Transmit Clock (MII interface) or Ethernet Reference Clock (RMII interface).
							I/O	**SSP1_SCK —** Serial clock for SSP1.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**CLKOUT —** Clock output pin.
							-	**R —** Function reserved.
							O	**I2S0_RX_MCLK —** I2S receive master clock.
							I/O	**I2S1_TX_SCK —** Transmit Clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the I^2S-bus specification.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
P3_5	C12	B7	173	121	[2]	N; PU	I/O	**GPIO1[15] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**SPIFI_SIO2 —** I/O lane 2 for SPIFI.
							I	**U1_RXD —** Receiver input for UART 1.
							I/O	**I2S0_TX_SDA —** I2S transmit data. It is driven by the transmitter and read by the receiver. Corresponds to the signal SD in the *I^2S-bus specification*.
							I/O	**I2S1_RX_WS —** Receive Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the *I^2S-bus specification*.
							O	**LCD_VD12 —** LCD data.
P3_6	B13	C7	174	122	[2]	N; PU	I/O	**GPIO0[6] —** General purpose digital input/output pin.
							I/O	**SPI_MISO —** Master In Slave Out for SPI.
							I/O	**SSP0_SSEL —** Slave Select for SSP0.
							I/O	**SPIFI_MISO —** Input 1 in SPIFI quad mode; SPIFI output IO1.
							-	**R —** Function reserved.
							I/O	**SSP0_MISO —** Master In Slave Out for SSP0.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P3_7	C11	D7	176	123	[2]	N; PU	-	**R —** Function reserved.
							I/O	**SPI_MOSI —** Master Out Slave In for SPI.
							I/O	**SSP0_MISO —** Master In Slave Out for SSP0.
							I/O	**SPIFI_MOSI —** Input I0 in SPIFI quad mode; SPIFI output IO0.
							I/O	**GPIO5[10] —** General purpose digital input/output pin.
							I/O	**SSP0_MOSI —** Master Out Slave in for SSP0.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P3_8	C10	E7	179	124	[2]	N; PU	-	**R —** Function reserved.
							I	**SPI_SSEL —** Slave Select for SPI. Note that this pin in an input pin only. The SPI in master mode cannot drive the CS input on the slave. Any GPIO pin can be used for SPI chip select in master mode.
							I/O	**SSP0_MOSI —** Master Out Slave in for SSP0.
							I/O	**SPIFI_CS —** SPIFI serial flash chip select.
							I/O	**GPIO5[11] —** General purpose digital input/output pin.
							I/O	**SSP0_SSEL —** Slave Select for SSP0.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
P5_0	N3	-	53	37	[2]	N; PU	I/O	**GPIO2[9] —** General purpose digital input/output pin.
							O	**MCOB2 —** Motor control PWM channel 2, output B.
							I/O	**EMC_D12 —** External memory data line 12.
							-	**R —** Function reserved.
							I	**U1_DSR —** Data Set Ready input for UART 1.
							I	**T1_CAP0 —** Capture input 0 of timer 1.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P5_1	P3	-	55	39	[2]	N; PU	I/O	**GPIO2[10] —** General purpose digital input/output pin.
							I	**MCI2 —** Motor control PWM channel 2, input.
							I/O	**EMC_D13 —** External memory data line 13.
							-	**R —** Function reserved.
							O	**U1_DTR —** Data Terminal Ready output for UART 1. Can also be configured to be an RS-485/EIA-485 output enable signal for UART 1.
							I	**T1_CAP1 —** Capture input 1 of timer 1.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P5_2	R4	-	63	46	[2]	N; PU	I/O	**GPIO2[11] —** General purpose digital input/output pin.
							I	**MCI1 —** Motor control PWM channel 1, input.
							I/O	**EMC_D14 —** External memory data line 14.
							-	**R —** Function reserved.
							O	**U1_RTS —** Request to Send output for UART 1. Can also be configured to be an RS-485/EIA-485 output enable signal for UART 1.
							I	**T1_CAP2 —** Capture input 2 of timer 1.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P5_3	T8	-	76	54	[2]	N; PU	I/O	**GPIO2[12] —** General purpose digital input/output pin.
							I	**MCI0 —** Motor control PWM channel 0, input.
							I/O	**EMC_D15 —** External memory data line 15.
							-	**R —** Function reserved.
							I	**U1_RI —** Ring Indicator input for UART 1.
							I	**T1_CAP3 —** Capture input 3 of timer 1.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
P6_7	J13	-	123	85	[2]	N; PU	-	**R —** Function reserved.
							I/O	**EMC_A15 —** External memory address line 15.
							I/O	**SGPIO6 —** General purpose digital input/output pin.
							O	**USB0_IND1 —** USB0 port indicator LED control output 1.
							I/O	**GPIO5[15] —** General purpose digital input/output pin.
							O	**T2_MAT0 —** Match output 0 of timer 2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P6_8	H13	-	125	86	[2]	N; PU	-	**R —** Function reserved.
							I/O	**EMC_A14 —** External memory address line 14.
							I/O	**SGPIO7 —** General purpose digital input/output pin.
							O	**USB0_IND0 —** USB0 port indicator LED control output 0.
							I/O	**GPIO5[16] —** General purpose digital input/output pin.
							O	**T2_MAT1 —** Match output 1 of timer 2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P6_9	J15	F8	139	97	[2]	N; PU	I/O	**GPIO3[5] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**$\overline{\text{EMC\_DYCS0}}$ —** SDRAM chip select 0.
							-	**R —** Function reserved.
							O	**T2_MAT2 —** Match output 2 of timer 2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P6_10	H15	-	142	100	[2]	N; PU	I/O	**GPIO3[6] —** General purpose digital input/output pin.
							O	**$\overline{\text{MCABORT}}$ —** Motor control PWM, LOW-active fast abort.
							-	**R —** Function reserved.
							O	**EMC_DQMOUT1 —** Data mask 1 used with SDRAM and static devices.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
Clock pins								
CLK0	N5	K3	62	45	[4]	O; PU	O	**EMC_CLK0 —** SDRAM clock 0.
							O	**CLKOUT —** Clock output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**SD_CLK —** SD/MMC card clock.
							O	**EMC_CLK01 —** SDRAM clock 0 and clock 1 combined.
							I/O	**SSP1_SCK —** Serial clock for SSP1.
							I	**ENET_TX_CLK (ENET_REF_CLK) —** Ethernet Transmit Clock (MII interface) or Ethernet Reference Clock (RMII interface).
CLK1	T10	-	-	-	[4]	O; PU	O	**EMC_CLK1 —** SDRAM clock 1.
							O	**CLKOUT —** Clock output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**CGU_OUT0 —** CGU spare clock output 0.
							-	**R —** Function reserved.
							O	**I2S1_TX_MCLK —** I2S1 transmit master clock.
CLK2	D14	K6	141	99	[4]	O; PU	O	**EMC_CLK3 —** SDRAM clock 3.
							O	**CLKOUT —** Clock output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**SD_CLK —** SD/MMC card clock.
							O	**EMC_CLK23 —** SDRAM clock 2 and clock 3 combined.
							O	**I2S0_TX_MCLK —** I2S transmit master clock.
							I/O	**I2S1_RX_SCK —** Receive Clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the I^2S-bus specification.
CLK3	P12	-	-	-	[4]	O; PU	O	**EMC_CLK2 —** SDRAM clock 2.
							O	**CLKOUT —** Clock output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**CGU_OUT1 —** CGU spare clock output 1.
							-	**R —** Function reserved.
							I/O	**I2S1_RX_SCK —** Receive Clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the I^2S-bus specification.

7.5 AHB multilayer matrix

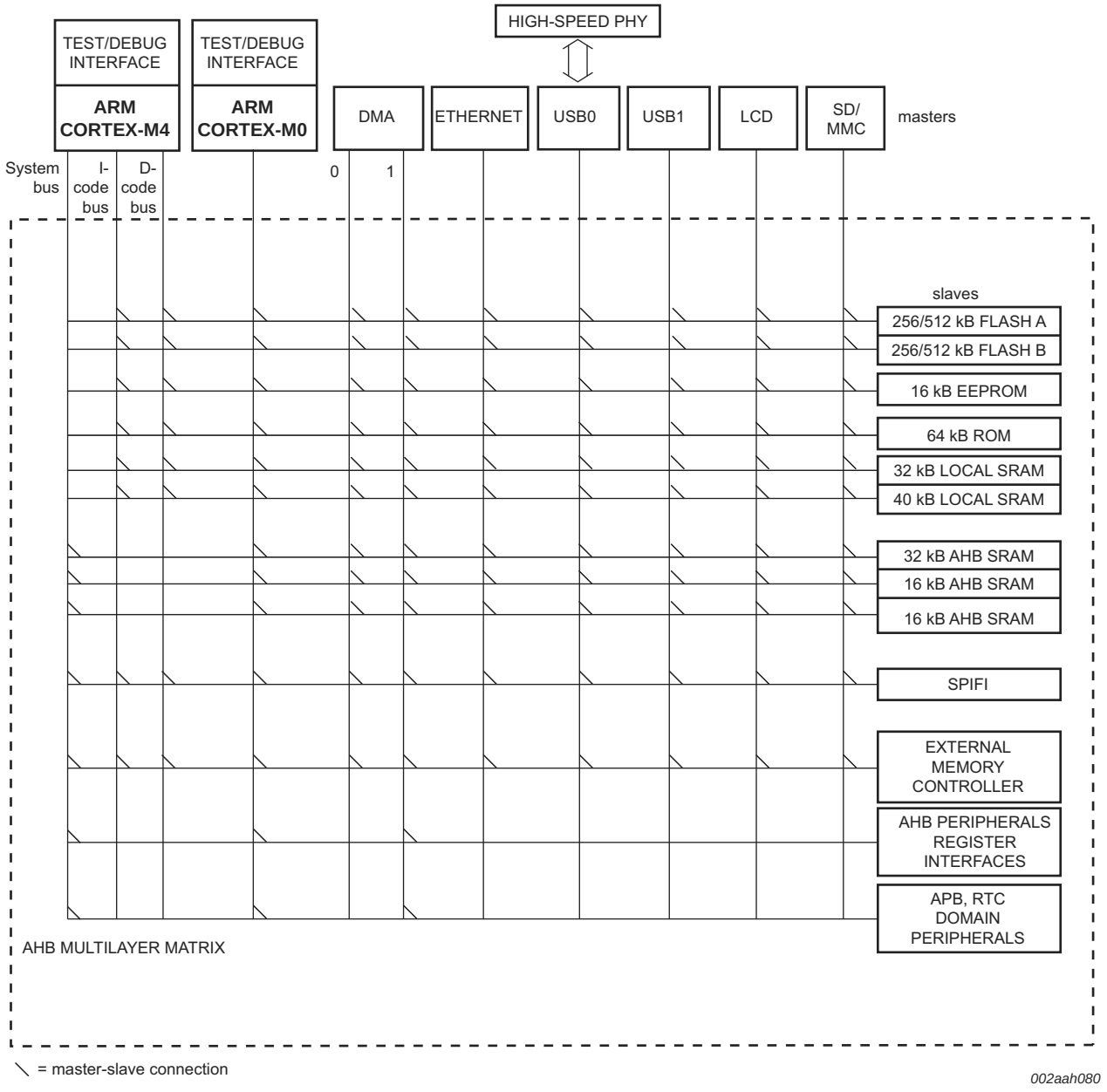


Fig 6. AHB multilayer matrix master and slave connections

7.6 Nested Vectored Interrupt Controller (NVIC)

The NVIC is an integral part of the Cortex-M4. The tight coupling to the CPU allows for low interrupt latency and efficient processing of late arriving interrupts.

The ARM Cortex-M0 co-processor has its own NVIC with 32 vectored interrupts. Most peripheral interrupts are shared between the Cortex-M0 and Cortex-M4 NVICs.

Remark: Any interrupt can wake up the ARM Cortex-M4 from sleep mode if enabled in the NVIC.

7.9 Global Input Multiplexer Array (GIMA)

The GIMA allows to route signals to event-driven peripheral targets like the SCTimer/PWM, timers, event router, or the ADCs.

7.9.1 Features

- Single selection of a source.
- Signal inversion.
- Can capture a pulse if the input event source is faster than the target clock.
- Synchronization of input event and target clock.
- Single-cycle pulse generation for target.

7.10 On-chip static RAM

The LPC435x/3x/2x/1x support up to 136 kB SRAM with separate bus master access for higher throughput and individual power control for low power operation.

7.11 On-chip flash memory

The LPC435x/3x/2x/1x contain up to 1 MB of dual-bank flash program memory. With dual-bank flash memory, the user code can write or erase one flash bank while reading the other flash bank without interruption. A two-port flash accelerator maximizes the flash performance.

In-System Programming (ISP) and In-Application Programming (IAP) routines for programming the flash memory are provided in the Boot ROM.

7.12 EEPROM

The LPC435x/3x/2x/1x contain 16 kB of on-chip byte-erasable and byte-programmable EEPROM memory.

The EEPROM memory is divided into 128 pages. The user can access pages 1 through 127. Page 128 is protected.

7.13 Boot ROM

The internal ROM memory is used to store the boot code of the LPC435x/3x/2x/1x. After a reset, the ARM processor will start its code execution from this memory.

The boot ROM memory includes the following features:

- The ROM memory size is 64 kB.
- Supports booting from external static memory such as NOR flash, SPI flash, quad SPI flash, USB0, and USB1.
- Includes API for OTP programming.
- Includes a flexible USB device stack that supports Human Interface Device (HID), Mass Storage Class (MSC), and Device Firmware Upgrade (DFU) drivers.

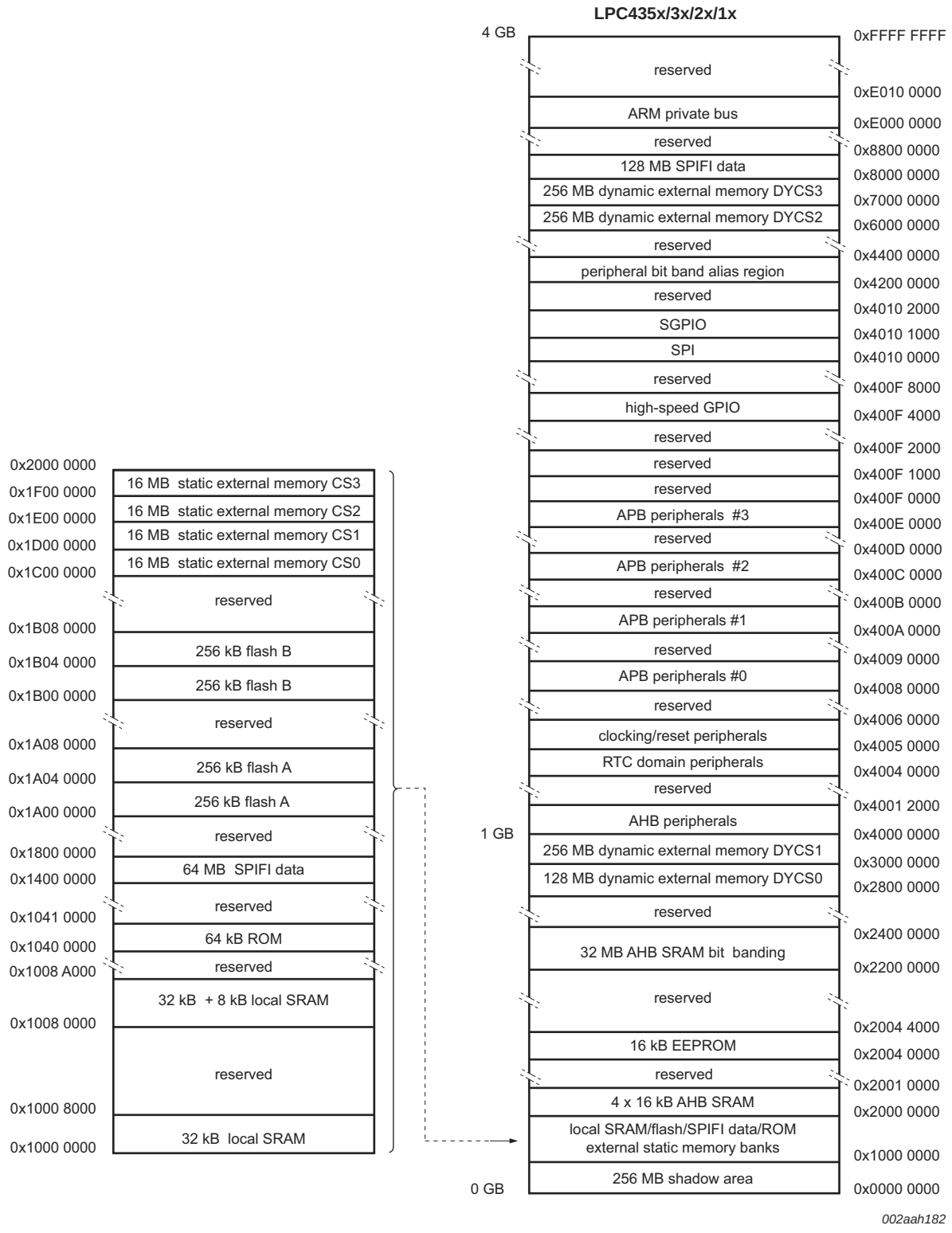


Fig 7. LPC435x/3x/2x/1x Memory mapping (overview)

- Alarm interrupt can be generated for a specific date/time.

7.22.1.2 Event monitor/recorder

The event monitor/recorder allows recording and creating a time stamp of events related to the WAKEUP pins. Sensors report changes to the state of the WAKEUP pins, and the event monitor/recorder stores records of such events. The event recorder can be powered by the backup battery.

The event monitor/recorder can monitor the integrity of the device and record any tampering events.

Features

- Supports three digital event inputs in the VBAT power domain.
- An event is defined as a level change at the digital event inputs.
- For each event channel, two timestamps mark the first and the last occurrence of an event. Each channel also has a dedicated counter tracking the total number of events. Timestamp values are taken from the RTC.
- Runs in VBAT power domain, independent of system power supply. The event/recorder/monitor can therefore operate in Deep power-down mode.
- Low power consumption.
- Interrupt available if system is running.
- A qualified event can be used as a wake-up trigger.
- State of event interrupts accessible by software through GPIO.

7.22.2 Alarm timer

The alarm timer is a 16-bit timer and counts down at 1 kHz from a preset value generating alarms in intervals of up to 1 min. The counter triggers a status bit when it reaches 0x00 and asserts an interrupt if enabled.

The alarm timer is part of the RTC power domain and can be battery powered.

7.23 System control

7.23.1 Configuration registers (CREG)

The following settings are controlled in the configuration register block:

- BOD trip settings
- Oscillator output
- DMA-to-peripheral muxing
- Ethernet mode
- Memory mapping
- Timer/USART inputs
- Enabling the USB controllers

In addition, the CREG block contains the part identification and part configuration information.

Table 11. Static characteristics *…continued*
T_{amb} = −40 °C to +105 °C, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
V_{IC}	common-mode input voltage	high-speed mode		−50	200	500	mV
		full-speed/low-speed mode		800	-	2500	mV
		chirp mode		−50	-	600	mV
$V_{i(dif)}$	differential input voltage			100	400	1100	mV
USB1 pins (USB1_DP/USB1_DM)[17]							
I_{OZ}	OFF-state output current	0 V < V_I < 3.3 V	[17]	-	-	±10	μA
V_{BUS}	bus supply voltage		[18]	-	-	5.25	V
V_{DI}	differential input sensitivity voltage	|(D+) − (D−)|		0.2	-	-	V
V_{CM}	differential common mode voltage range	includes V_{DI} range		0.8	-	2.5	V
$V_{th(rs)se}$	single-ended receiver switching threshold voltage			0.8	-	2.0	V
V_{OL}	LOW-level output voltage for low-/full-speed	R_L of 1.5 kΩ to 3.6 V		-	-	0.18	V
V_{OH}	HIGH-level output voltage (driven) for low-/full-speed	R_L of 15 kΩ to GND		2.8	-	3.5	V
C_{trans}	transceiver capacitance	pin to GND		-	-	20	pF
Z_{DRV}	driver output impedance for driver which is not high-speed capable	with 33 Ω series resistor; steady state drive	[19]	36	-	44.1	Ω

[1] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

[2] The recommended operating condition for the battery supply is $V_{DD(REG)(3V3)} > V_{BAT} + 0.2$ V. Special conditions for $V_{DD(REG)(3V3)}$ apply when writing to the flash and EEPROM. See Table 14 and Table 15.

[3] Pin VPP should either be not connected (when OTP does not need to be programmed) or tied to pins VDDIO and VDDREG to ensure the same ramp-up time for both supply voltages.

[4] $V_{DD(REG)(3V3)}$ = 3.3 V; $V_{DD(IO)}$ = 3.3 V; T_{amb} = 25 °C.

[5] PLL1 disabled; IRC running; CCLK = 12 MHz.

[6] V_{BAT} = 3.6 V.

[7] T_{amb} = -40 °C to +105 °C; $V_{DD(IO)} = V_{DDA}$ = 3.6 V; over entire frequency range CCLK = 12 MHz to 204 MHz; in active mode, sleep mode; deep-sleep mode, power-down mode, and deep power-down mode.

[8] On pin VBAT; T_{amb} = 25 °C.

[9] V_{ps} corresponds to the output of the power switch (see Table 9) which is determined by the greater of V_{BAT} and $V_{DD(Reg)(3V3)}$.

[10] $V_{DDA(3V3)}$ = 3.3 V; T_{amb} = 25 °C.

[11] Allowed as long as the current limit does not exceed the maximum current allowed by the device.

[12] To V_{SS}.

[13] The values specified are simulated and absolute values.

[14] The weak pull-up resistor is connected to the $V_{DD(IO)}$ rail and pulls up the I/O pin to the $V_{DD(IO)}$ level.

[15] The input cell disables the weak pull-up resistor when the applied input voltage exceeds $V_{DD(IO)}$.

11.2 Wake-up times

Table 17. Dynamic characteristic: Wake-up from Deep-sleep, Power-down, and Deep power-down modes

T_{amb} = −40 °C to +105 °C

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
t_{wake}	wake-up time	from Sleep mode	[2]	$3 \times T_{cy(clk)}$	$5 \times T_{cy(clk)}$	-	ns
		from Deep-sleep and Power-down mode		12	51	-	µs
		from Deep power-down mode		-	200	-	µs
		after reset		-	200	-	µs

[1] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

[2] $T_{cy(clk)}$ = 1/CCLK with CCLK = CPU clock frequency.

11.3 External clock for oscillator in slave mode

Remark: The input voltage on the XTAL1/2 pins must be ≤ 1.2 V (see Table 11). For connecting the oscillator to the XTAL pins, also see Section 13.2 and Section 13.4.

Table 18. Dynamic characteristic: external clock

T_{amb} = −40 °C to +105 °C; $V_{DD(IO)}$ over specified ranges.[1]

Symbol	Parameter	Conditions		Min	Max	Unit
f_{osc}	oscillator frequency			1	25	MHz
$T_{cy(clk)}$	clock cycle time			40	1000	ns
t_{CHCX}	clock HIGH time			$T_{cy(clk)} \times 0.4$	$T_{cy(clk)} \times 0.6$	ns
t_{CLCX}	clock LOW time			$T_{cy(clk)} \times 0.4$	$T_{cy(clk)} \times 0.6$	ns

[1] Parameters are valid over operating temperature range unless otherwise specified.

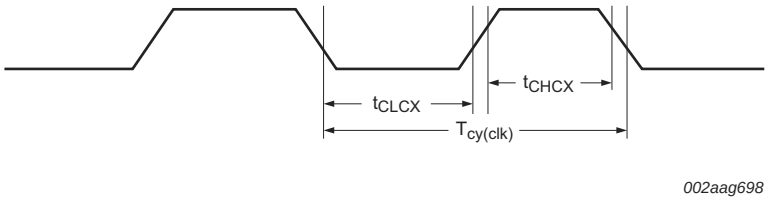


Fig 26. External clock timing (with an amplitude of at least $V_{i(RMS)}$ = 200 mV)

Table 27. Dynamic characteristics: SSP pins in SPI mode

T_{amb} = −40 °C to +105 °C; 2.4 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V; 2.7 V ≤ $V_{DD(IO)}$ ≤ 3.6 V; C_L = 20 pF; sampled at 10 % and 90 % of the signal level; EHS = 1 for all pins. Simulated values.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
t_{lag}	lag time	continuous transfer mode SPI mode; CPOL = 0; CPHA = 0		0.5 x $T_{cy(clk)}$ + 1.5	-	-	ns
		SPI mode; CPOL = 0; CPHA = 1		$T_{cy(clk)}$ + 1.5	-	-	ns
		SPI mode; CPOL = 1; CPHA = 0		0.5 × $T_{cy(clk)}$ + 1.5	-	-	ns
		SPI mode; CPOL = 1; CPHA = 1		$T_{cy(clk)}$ + 1.5	-	-	ns
		synchronous serial frame mode		$T_{cy(clk)}$ + 1.5	-	-	ns
		microwire frame format		0.5 × $T_{cy(clk)}$	-	-	ns
t_d	delay time	continuous transfer mode SPI mode; CPOL = 0; CPHA = 0		-	0.5 × $T_{cy(clk)}$	-	ns
		SPI mode; CPOL = 0; CPHA = 1		-	n/a	-	ns
		SPI mode; CPOL = 1; CPHA = 0		-	0.5 × $T_{cy(clk)}$	-	ns
		SPI mode; CPOL = 1; CPHA = 1		-	n/a	-	ns
		synchronous serial frame mode		-	$T_{cy(clk)}$	-	ns
		microwire frame format		-	n/a	-	ns

[1] $T_{cy(clk)}$ = (SSPCLKDIV × (1 + SCR) × CPSDVSR) / f_{main}. The clock cycle time derived from the SPI bit rate $T_{cy(clk)}$ is a function of the main clock frequency f_{main}, the SSP peripheral clock divider (SSPCLKDIV), the SSP SCR parameter (specified in the SSP0CR0 register), and the SSP CPSDVSR parameter (specified in the SSP clock prescale register).

[2] $T_{cy(clk)} \geq 12 \times T_{cy(PCLK)}$.

11.13 SPI interface

Table 28. Dynamic characteristics: SPI

T_{amb} = −40 °C to +105 °C; 2.4 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V; 2.7 V ≤ $V_{DD(IO)}$ ≤ 3.6 V. Simulated values.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$T_{cy(PCLK)}$	PCLK cycle time			5			ns
$T_{cy(clk)}$	clock cycle time		[1]	40	-	-	ns
Master							
t_{DS}	data set-up time			7.2	-	-	ns
t_{DH}	data hold time			0	-	-	ns
$t_{v(Q)}$	data output valid time			-	-	3.7	ns
$t_{h(Q)}$	data output hold time			-	-	1.2	ns
Slave							
t_{DS}	data set-up time			1.2	-	-	ns
t_{DH}	data hold time			$3 \times T_{cy(PCLK)} + 0.54$	-	-	ns
$t_{v(Q)}$	data output valid time			-	-	$3 \times T_{cy(PCLK)} + 9.7$	ns
$t_{h(Q)}$	data output hold time			-	-	$2 \times T_{cy(PCLK)} + 7.1$	ns

[1] $T_{cy(clk)}$ = 8/BASE_SPI_CLK. $T_{cy(PCLK)}$ = 1/BASE_SPI_CLK.

11.14 SSP/SPI timing diagrams

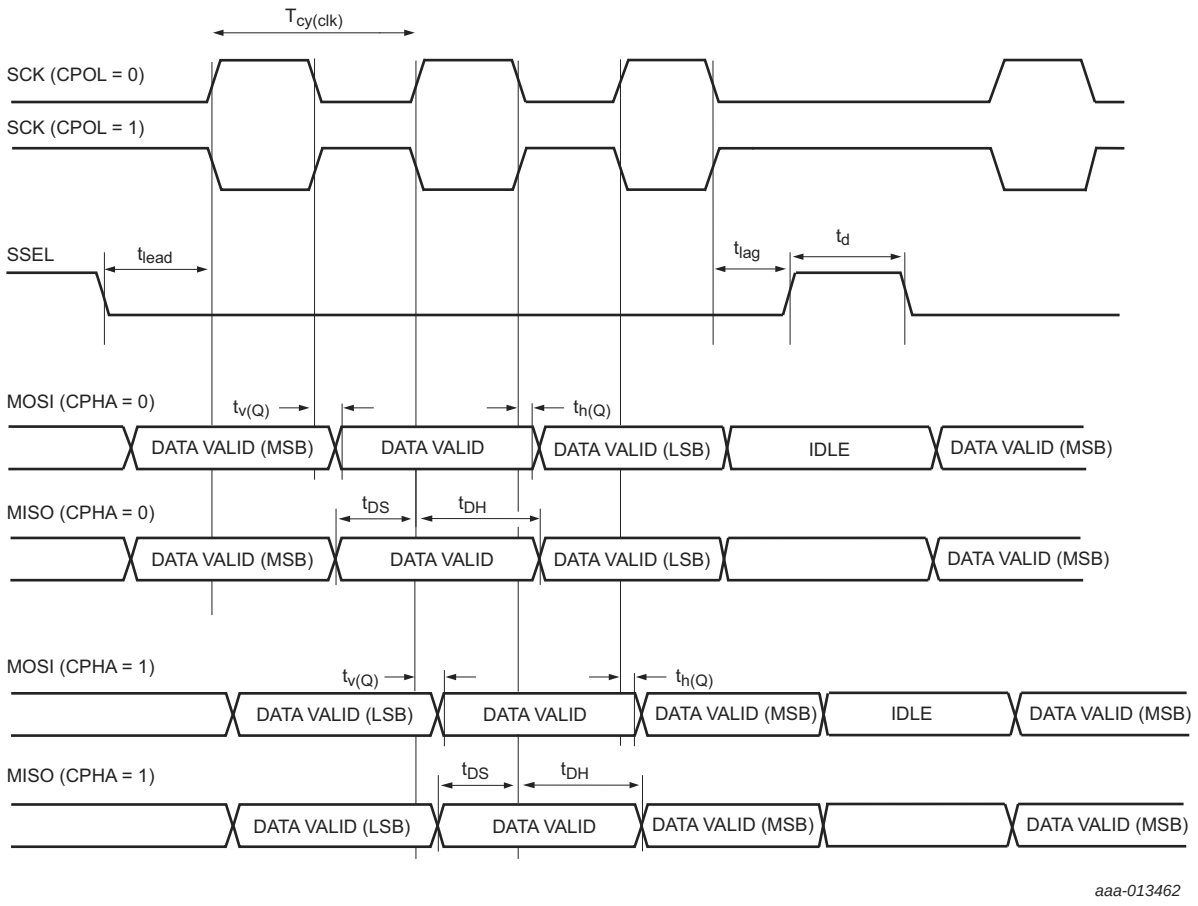


Fig 31. SSP in SPI mode and SPI master timing

Table 36. Dynamic characteristics: Ethernet

T_{amb} = −40 °C to 105 °C, 2.4 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V; 2.7 V ≤ $V_{DD(IO)}$ ≤ 3.6 V. Values guaranteed by design.

Symbol	Parameter	Conditions		Min	Max	Unit
RMII mode						
f_{clk}	clock frequency	for ENET_RX_CLK	[1]	-	50	MHz
δ_{clk}	clock duty cycle		[1]	50	50	%
t_{su}	set-up time	for ENET_TXDn, ENET_TX_EN, ENET_RXDn, ENET_RX_ER, ENET_RX_DV	[1][2]	4	-	ns
t_h	hold time	for ENET_TXDn, ENET_TX_EN, ENET_RXDn, ENET_RX_ER, ENET_RX_DV	[1][2]	2	-	ns
MII mode						
f_{clk}	clock frequency	for ENET_TX_CLK	[1]	-	25	MHz
δ_{clk}	clock duty cycle		[1]	50	50	%
t_{su}	set-up time	for ENET_TXDn, ENET_TX_EN, ENET_TX_ER	[1][2]	4	-	ns
t_h	hold time	for ENET_TXDn, ENET_TX_EN, ENET_TX_ER	[1][2]	2	-	ns
f_{clk}	clock frequency	for ENET_RX_CLK	[1]	-	25	MHz
δ_{clk}	clock duty cycle		[1]	50	50	%
t_{su}	set-up time	for ENET_RXDn, ENET_RX_ER, ENET_RX_DV	[1][2]	4	-	ns
t_h	hold time	for ENET_RXDn, ENET_RX_ER, ENET_RX_DV	[1][2]	2	-	ns

[1] Output drivers can drive a load ≥ 25 pF accommodating over 12 inch of PCB trace and the input capacitance of the receiving device.

[2] Timing values are given from the point at which the clock signal waveform crosses 1.4 V to the valid input or output level.

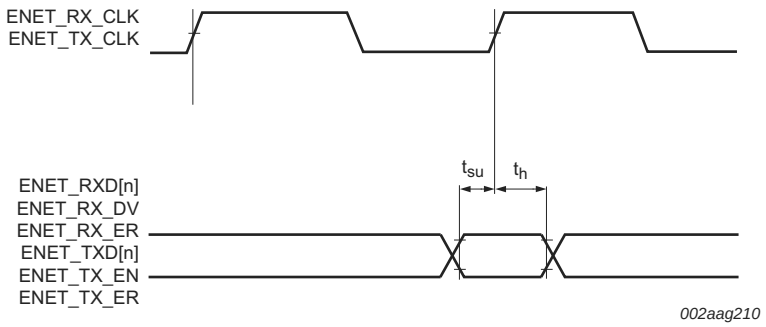


Fig 39. Ethernet timing

Table 42. LCD panel connections for STN dual panel mode

External pin	4-bit mono STN dual panel		8-bit mono STN dual panel		Color STN dual panel	
	LPC43xx pin used	LCD function	LPC43xx pin used	LCD function	LPC43xx pin used	LCD function
LCD_VD2	P4_3	UD[2]	P4_3	UD[2]	P4_3	UD[2]
LCD_VD1	P4_4	UD[1]	P4_4	UD[1]	P4_4	UD[1]
LCD_VD0	P4_1	UD[0]	P4_1	UD[0]	P4_1	UD[0]
LCD_LP	P7_6	LCDLP	P7_6	LCDLP	P7_6	LCDLP
LCD_ENAB/ LCDM	P4_6	LCDENAB/ LCDM	P4_6	LCDENAB/ LCDM	P4_6	LCDENAB/ LCDM
LCD_FP	P4_5	LCDFP	P4_5	LCDFP	P4_5	LCDFP
LCD_DCLK	P4_7	LCDDCLK	P4_7	LCDDCLK	P4_7	LCDDCLK
LCD_LE	P7_0	LCDLE	P7_0	LCDLE	P7_0	LCDLE
LCD_PWR	P7_7	LCDPWR	P7_7	LCDPWR	P7_7	LCDPWR
GP_CLKIN	PF_4	LCDCLKIN	PF_4	LCDCLKIN	PF_4	LCDCLKIN

Table 43. LCD panel connections for TFT panels

External pin	TFT 12 bit (4:4:4 mode)		TFT 16 bit (5:6:5 mode)		TFT 16 bit (1:5:5:5 mode)		TFT 24 bit	
	LPC43xx pin used	LCD function	LPC43xx pin used	LCD function	LPC43xx pin used	LCD function	LPC43xx pin used	LCD function
LCD_VD23	PB_0	BLUE3	PB_0	BLUE4	PB_0	BLUE4	PB_0	BLUE7
LCD_VD22	PB_1	BLUE2	PB_1	BLUE3	PB_1	BLUE3	PB_1	BLUE6
LCD_VD21	PB_2	BLUE1	PB_2	BLUE2	PB_2	BLUE2	PB_2	BLUE5
LCD_VD20	PB_3	BLUE0	PB_3	BLUE1	PB_3	BLUE1	PB_3	BLUE4
LCD_VD19	-	-	P7_1	BLUE0	P7_1	BLUE0	P7_1	BLUE3
LCD_VD18	-	-	-	-	P7_2	intensity	P7_2	BLUE2
LCD_VD17	-	-	-	-	-	-	P7_3	BLUE1
LCD_VD16	-	-	-	-	-	-	P7_4	BLUE0
LCD_VD15	PB_4	GREEN3	PB_4	GREEN5	PB_4	GREEN4	PB_4	GREEN7
LCD_VD14	PB_5	GREEN2	PB_5	GREEN4	PB_5	GREEN3	PB_5	GREEN6
LCD_VD13	PB_6	GREEN1	PB_6	GREEN3	PB_6	GREEN2	PB_6	GREEN5
LCD_VD12	P8_3	GREEN0	P8_3	GREEN2	P8_3	GREEN1	P8_3	GREEN4
LCD_VD11	-	-	P4_9	GREEN1	P4_9	GREEN0	P4_9	GREEN3
LCD_VD10	-	-	P4_10	GREEN0	P4_10	intensity	P4_10	GREEN2
LCD_VD9	-	-	-	-	-	-	P4_8	GREEN1
LCD_VD8	-	-	-	-	-	-	P7_5	GREEN0
LCD_VD7	P8_4	RED3	P8_4	RED4	P8_4	RED4	P8_4	RED7
LCD_VD6	P8_5	RED2	P8_5	RED3	P8_5	RED3	P8_5	RED6
LCD_VD5	P8_6	RED1	P8_6	RED2	P8_6	RED2	P8_6	RED5
LCD_VD4	P8_7	RED0	P8_7	RED1	P8_7	RED1	P8_7	RED4
LCD_VD3	-	-	P4_2	RED0	P4_2	RED0	P4_2	RED3
LCD_VD2	-	-	-	-	P4_3	intensity	P4_3	RED2
LCD_VD1	-	-	-	-	-	-	P4_4	RED1

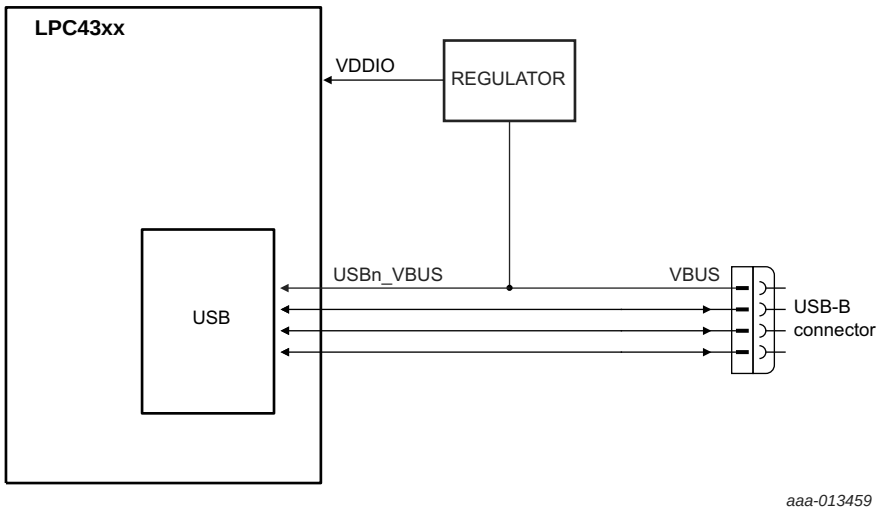


Fig 49. USB interface on a bus-powered device

Remark: If the VBUS function of the USB1 interface is not connected, configure the pin function for GPIO using the function control bits in the SYSCON block.

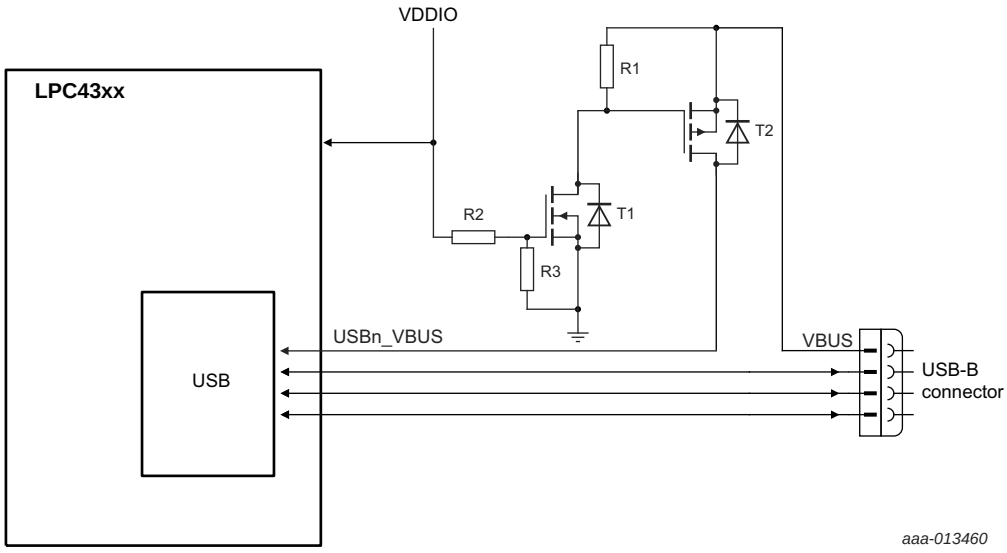


Fig 50. USB interface for USB operating in OTG mode

Remark: In OTG mode, it is important to be able to detect the VBUS level and to charge and discharge VBUS. This requires adding active devices that disconnect the link when VDDIO is not present.

Table 47. Revision history *…continued*

Document ID	Release date	Data sheet status	Change notice	Supersedes
Modifications:	• SD/MMC timing data updated. See Table 35 “Dynamic characteristics: SD/MMC”. • IEEE standard 802.3 compliance added to Section 11.18. Covers Ethernet dynamic characteristics of ENET_MDIO and ENET_MDC signals. • SSP master mode timing diagram updated with SSEL timing parameters. See Figure 31 “SSP in SPI mode and SPI master timing”. • Parameters t_{lead}, t_{lag}, and t_d added in Table 25 “Dynamic characteristics: SSP pins in SPI mode”. • Parameter t_{CSLWEL} with condition PB = 1 corrected: (WAITWEN + 1) × $T_{cy(clk)}$ added. See Table 29 “Dynamic characteristics: Static asynchronous external memory interface”. • Parameter $t_{CSLBLSL}$ with condition PB = 0 corrected: (WAITWEN + 1) × $T_{cy(clk)}$ added. See Table 29 “Dynamic characteristics: Static asynchronous external memory interface”. • Removed restriction on C_CAN bus usage. See CAN.1 errata in Ref. 2. • General-purpose OTP size corrected.			
LPC435X_3X_2X_1X v.3	20121206	Preliminary data sheet	-	LPC4357_53_37_33 v.2.1
Modifications:	• TFBGA180 packages removed. • Part LPC432x and LPC431x added. • SCT dither engine added and SCT bi-directional event enable features added. • Figure 10 “Dual-core debug configuration” added. • T = 105 °C data added in Figure 20 to Figure 23. • Change symbol names and parameter names in Table 21. • Parameter I_{LH} updated for condition V_I = 5 V and T_{amb} = 25 °C/105 °C in Table 11. • Power consumption data added in Section 10.1. • SPIFI dynamic characteristics added in Section 11.16. • IRC accuracy corrected to ± 2 % for T_{amb} = -40 °C to 0 °C and T_{amb} = 85 °C to 105 °C. • Pull-up and Pull-down current data (Figure 24 and Figure 25) updated with data for T_{amb} = 105 °C. • SPIFI maximum data rate changed to 52 MB per second. • Recommendation for V_{BAT} use added: The recommended operating condition for the battery supply is $V_{DD(REG)(3V3)} > V_{BAT}$ + 0.2 V. • Table 14 “Band gap characteristics” added. • Section 7.23.9 “Power Management Controller (PMC)” added. • Description of ADC pins on digital/analog input pins changed. Each input to the ADC is connected to ADC0 and ADC1. See Table 3. • OTP memory size changed to 64 bit. • Use of C_CAN peripheral restricted in Section 2. • ADC channels limited to a total of 8 channels shared between ADC0 and ADC1.			
LPC4357_53_37_33 v.2.1	20120904	Preliminary data sheet	-	LPC4357_53_37_33 v.2
Modifications:	• SSP0 boot pin functions corrected in Table 5 and Table 4. Pin P3_3 = SSP0_SCK, pin P3_6 = SSP0_SSEL, pin P3_7 = SSP0_MISO, pin P3_8 = SSP0_MOSI. • SWD removed for ARM Cortex-M0. • BOD de-assertion levels added in Table 13. • Peripheral power consumption data added in Table 12. • Minimum value for all supply voltages changed to -0.5 V in Table 7.			